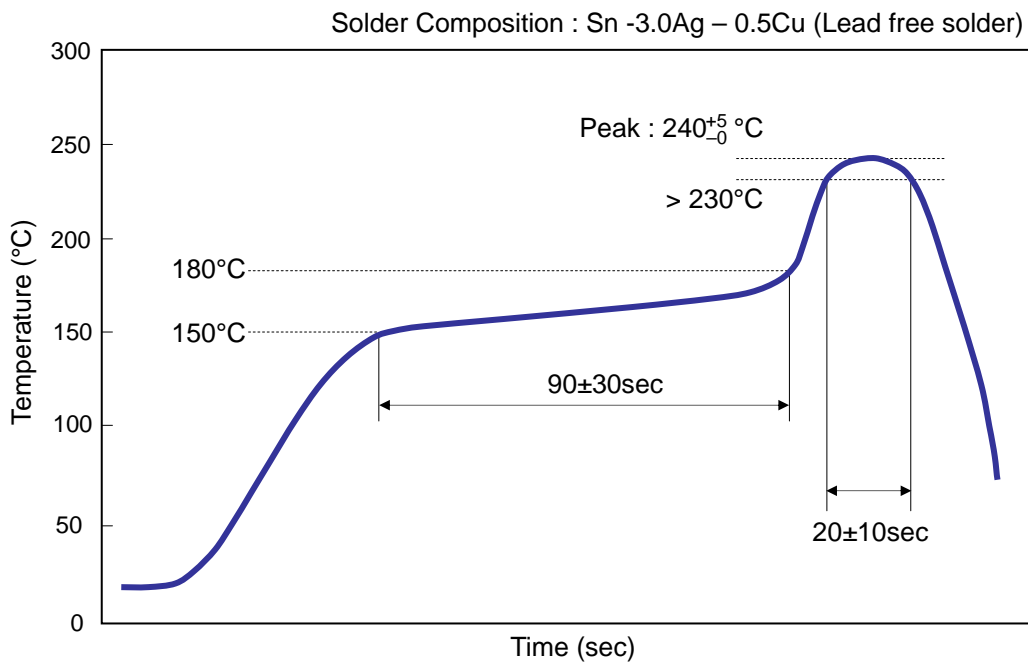


Lead-Free Reflow Soldering Temperature Profile



| Reflow portion | |
|---------------------------|--------------------------|
| Peak temperature / Time | 240°C / within 5sec |
| Above 230°C | 20±10sec |
| Pre-heat portion | |
| 150~180°C | 90±30sec |
| Testing point | Product surface |
| Product storage condition | 10~40°C, within 30~60%RH |

Note : While using the above recommended reflow temperature with the solder paste, please limit this process to 2 times only.